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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	12
Number of Macrocells	192
Number of Gates	3750
Number of I/O	124
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7192eqc160-12

Table 2. MAX 7000S Device Features

Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t_{PD} (ns)	5	5	6	6	7.5	7.5
t_{SU} (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t_{FSU} (ns)	2.5	2.5	2.5	2.5	3	3
t_{CO1} (ns)	3.2	3.2	4	3.9	4.7	4.7
f_{CNT} (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

…and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
  - MultiVolt™ I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
  - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
  - Six pin- or logic-driven output enable signals
  - Two global clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Features

Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			✓ *(1)*
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface *(2)*	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:
(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
(2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

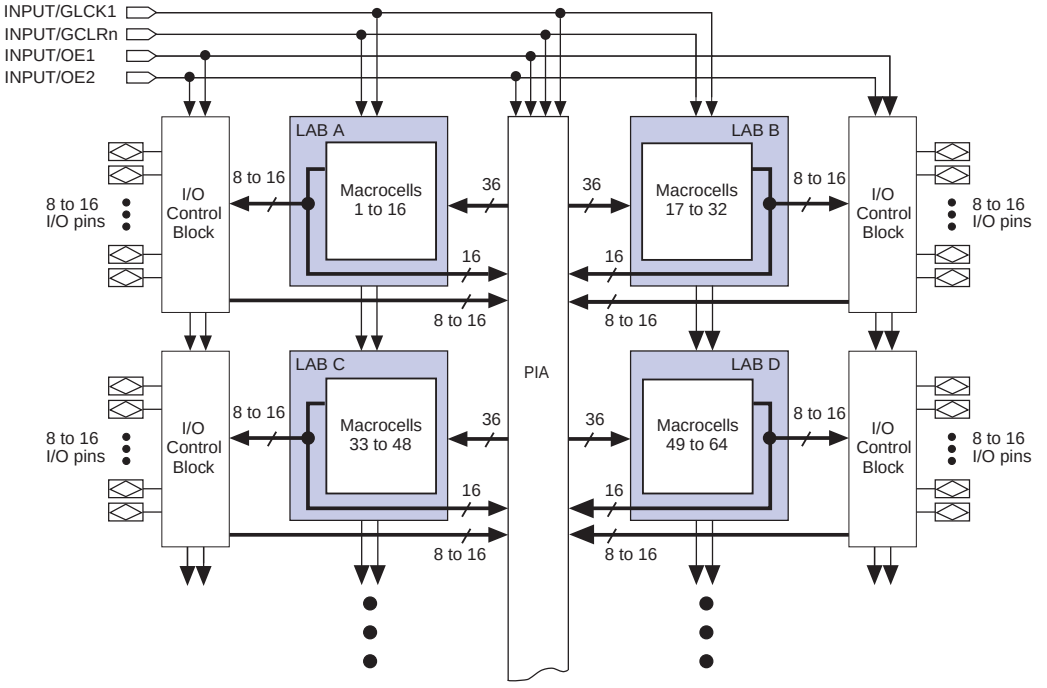
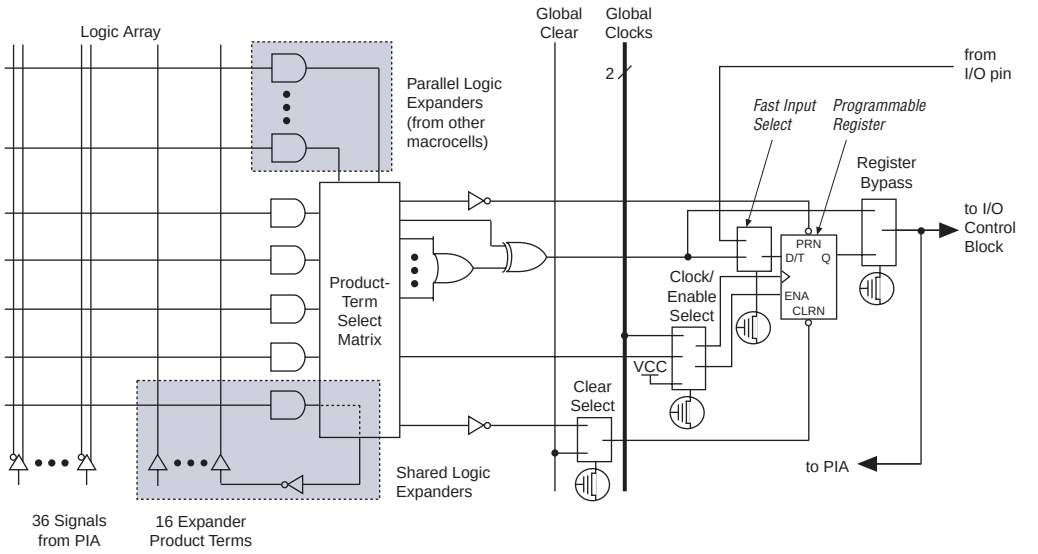


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Figure 4. MAX 7000E & MAX 7000S Device Macrocell



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-to-output performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, `GCLK1`, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, `GCLK1` or `GCLK2`.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (`GCLRn`). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms (“expanders”) that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time
t_{PPULSE} = Sum of the fixed times to erase, program, and verify the EEPROM cells
$Cycle_{PTCK}$ = Number of TCK cycles to program a device
f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time
t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
$Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The programming times described in Tables 6 through 8 are associated with the worst-case method using the enhanced ISP algorithm.

Table 6. MAX 7000S t_{PULSE} & $Cycle_{TCK}$ Values

Device	Programming		Stand-Alone Verification	
	t_{PPULSE} (s)	$Cycle_{PTCK}$	t_{VPULSE} (s)	$Cycle_{VTCK}$
EPM7032S	4.02	342,000	0.03	200,000
EPM7064S	4.50	504,000	0.03	308,000
EPM7128S	5.11	832,000	0.03	528,000
EPM7160S	5.35	1,001,000	0.03	640,000
EPM7192S	5.71	1,192,000	0.03	764,000
EPM7256S	6.43	1,603,000	0.03	1,024,000

Tables 7 and 8 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	s
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	s
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	s
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	s
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	s

Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	s
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	s
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	s
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	s
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	s

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.

For more information, see the *Programming Hardware Manufacturers*.

Design Security

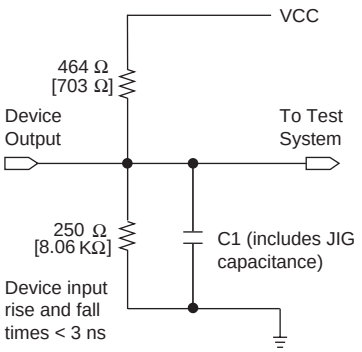
All MAX 7000 devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

Each MAX 7000 device is functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 10. Test patterns can be used and then erased during early stages of the production flow.

Figure 10. MAX 7000 AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices and outputs. Numbers without brackets are for 3.3-V devices and outputs.



QFP Carrier & Development Socket

MAX 7000 and MAX 7000E devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress.

For detailed information and carrier dimensions, refer to the *QFP Carrier & Development Socket Data Sheet*.

MAX 7000S devices are not shipped in carriers.

Operating Conditions

Tables 13 through 18 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

Table 13. MAX 7000 5.0-V Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	With respect to ground *(2)*	–2.0	7.0	V
V_I	DC input voltage		–2.0	7.0	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	Ceramic packages, under bias		150	° C
		PQFP and RQFP packages, under bias		135	° C

Table 14. MAX 7000 5.0-V Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(3)*, *(4)*, *(5)*	4.75 (4.50)	5.25 (5.50)	V
V_{CCIO}	Supply voltage for output drivers, 5.0-V operation	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	*(3)*, *(4)*, *(6)*	3.00 (3.00)	3.60 (3.60)	V
V_{CCISP}	Supply voltage during ISP	*(7)*	4.75	5.25	V
V_I	Input voltage		–0.5 *(8)*	V_{CCINT} + 0.5	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	For commercial use	0	70	° C
		For industrial use	–40	85	° C
T_J	Junction temperature	For commercial use	0	90	° C
		For industrial use	–40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Figure 13. Switching Waveforms

t_R & t_F < 3 ns.
Inputs are driven at 3 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.

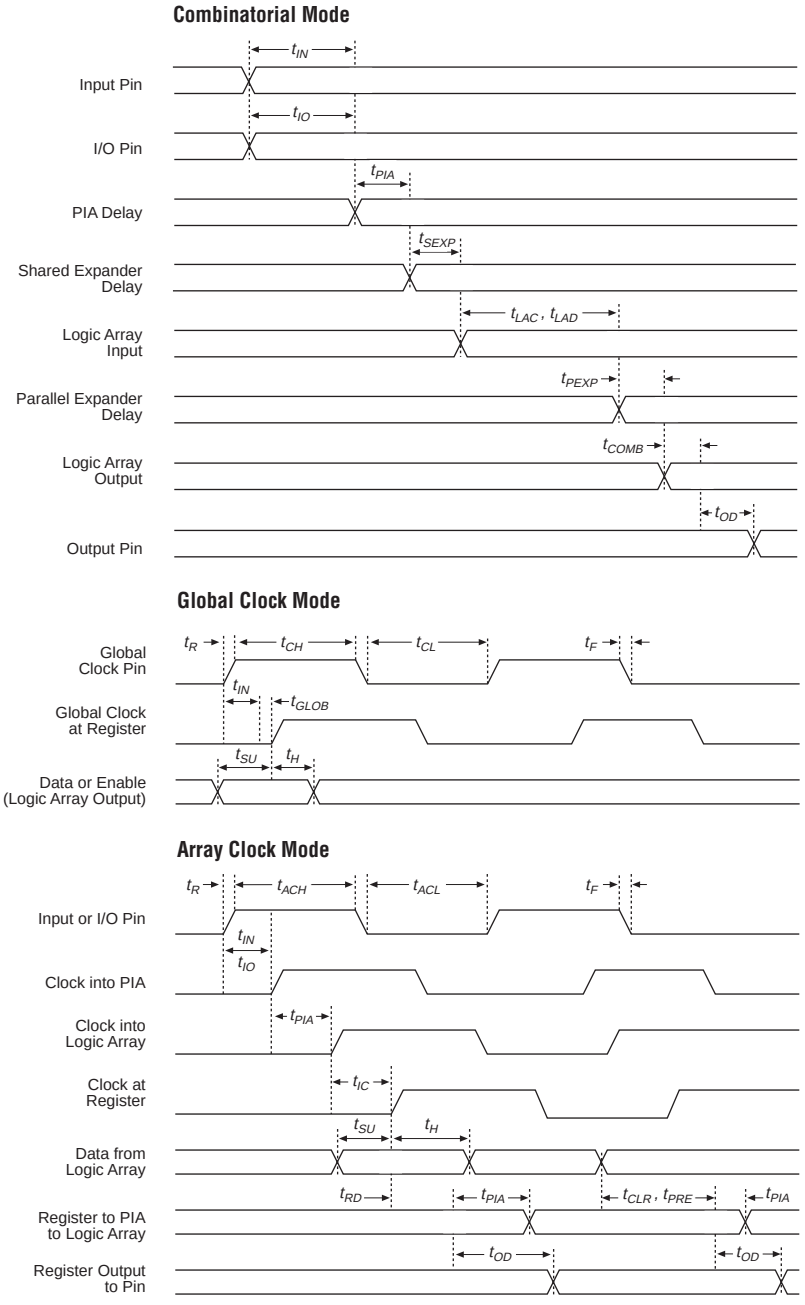


Table 24. MAX 7000 & MAX 7000E Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-12P)		MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			1.0		2.0	ns
t_{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t_{FIN}	Fast input delay	*(2)*		1.0		1.0	ns
t_{SEXP}	Shared expander delay			7.0		7.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.0	ns
t_{LAD}	Logic array delay			7.0		5.0	ns
t_{LAC}	Logic control array delay			5.0		5.0	ns
t_{IOE}	Internal output enable delay	*(2)*		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		2.0		4.0	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		5.0		7.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		7.0		7.0	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		10.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t_{SU}	Register setup time		1.0		4.0		ns
t_{H}	Register hold time		6.0		4.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	4.0		2.0		ns
t_{FH}	Register hold time of fast input	*(2)*	0.0		2.0		ns
t_{RD}	Register delay			2.0		1.0	ns
t_{COMB}	Combinatorial delay			2.0		1.0	ns
t_{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			7.0		5.0	ns
t_{GLOB}	Global control delay			2.0		0.0	ns
t_{PRE}	Register preset time			4.0		3.0	ns
t_{CLR}	Register clear time			4.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t_{LPA}	Low-power adder	*(8)*		12.0		12.0	ns

Table 26. MAX 7000 & MAX 7000E Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t_{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t_{FIN}	Fast input delay	*(2)*		2.0		–		4.0	ns
t_{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t_{LAD}	Logic array delay			6.0		6.0		8.0	ns
t_{LAC}	Logic control array delay			6.0		6.0		8.0	ns
t_{IOE}	Internal output enable delay	*(2)*		3.0		–		4.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		5.0		–		6.0	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		8.0		–		9.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		7.0		–		11.0	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		10.0		–		14.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t_{SU}	Register setup time		4.0		4.0		4.0		ns
t_{H}	Register hold time		4.0		4.0		5.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	2.0		–		4.0		ns
t_{FH}	Register hold time of fast input	*(2)*	2.0		–		3.0		ns
t_{RD}	Register delay			1.0		1.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t_{IC}	Array clock delay			6.0		6.0		8.0	ns
t_{EN}	Register enable time			6.0		6.0		8.0	ns
t_{GLOB}	Global control delay			1.0		1.0		3.0	ns
t_{PRE}	Register preset time			4.0		4.0		4.0	ns
t_{CLR}	Register clear time			4.0		4.0		4.0	ns
t_{PIA}	PIA delay			2.0		2.0		3.0	ns
t_{LPA}	Low-power adder	*(8)*		13.0		15.0		15.0	ns

Table 28. EPM7032S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PIA}	PIA delay	*(7)*		1.1		1.1		1.4		1.0	ns
t_{LPA}	Low-power adder	*(8)*		12.0		10.0		10.0		11.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
(5) The $\mathbf{f_{MAX}}$ values represent the highest frequency for pipelined data.
(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.
(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 29. EPM7064S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$\mathbf{t_{PD1}}$	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
$\mathbf{t_{PD2}}$	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
$\mathbf{t_{SU}}$	Global clock setup time		2.9		3.6		6.0		7.0		ns
$\mathbf{t_{H}}$	Global clock hold time		0.0		0.0		0.0		0.0		ns
$\mathbf{t_{FSU}}$	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
$\mathbf{t_{FH}}$	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
$\mathbf{t_{CO1}}$	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
$\mathbf{t_{CH}}$	Global clock high time		2.0		2.5		3.0		4.0		ns
$\mathbf{t_{CL}}$	Global clock low time		2.0		2.5		3.0		4.0		ns
$\mathbf{t_{ASU}}$	Array clock setup time		0.7		0.9		3.0		2.0		ns
$\mathbf{t_{AH}}$	Array clock hold time		1.8		2.1		2.0		3.0		ns

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 31. EPM7128S External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t_{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t_{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t_{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	3.0		3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	147.1		125.0		100.0		76.9		MHz
t_{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	147.1		125.0		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		166.7		125.0		100.0		MHz

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
(5) The $\mathbf{f_{MAX}}$ values represent the highest frequency for pipelined data.
(6) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.
(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Table 33. EPM7160S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
$\mathbf{t_{PD1}}$	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
$\mathbf{t_{PD2}}$	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
$\mathbf{t_{SU}}$	Global clock setup time		3.4		4.2		7.0		11.0		ns
$\mathbf{t_{H}}$	Global clock hold time		0.0		0.0		0.0		0.0		ns
$\mathbf{t_{FSU}}$	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
$\mathbf{t_{FH}}$	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
$\mathbf{t_{CO1}}$	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
$\mathbf{t_{CH}}$	Global clock high time		3.0		3.0		4.0		5.0		ns
$\mathbf{t_{CL}}$	Global clock low time		3.0		3.0		4.0		5.0		ns
$\mathbf{t_{ASU}}$	Array clock setup time		0.9		1.1		2.0		4.0		ns
$\mathbf{t_{AH}}$	Array clock hold time		1.7		2.1		3.0		4.0		ns
$\mathbf{t_{ACO1}}$	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
$\mathbf{t_{ACH}}$	Array clock high time		3.0		3.0		4.0		6.0		ns
$\mathbf{t_{ACL}}$	Array clock low time		3.0		3.0		4.0		6.0		ns
$\mathbf{t_{CPPW}}$	Minimum pulse width for clear and preset	*(2)*	2.5		3.0		4.0		6.0		ns
$\mathbf{t_{ODH}}$	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		1.0		ns
$\mathbf{t_{CNT}}$	Minimum global clock period			6.7		8.2		10.0		13.0	ns
$\mathbf{f_{CNT}}$	Maximum internal global clock frequency	*(4)*	149.3		122.0		100.0		76.9		MHz

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) *Note (1)*

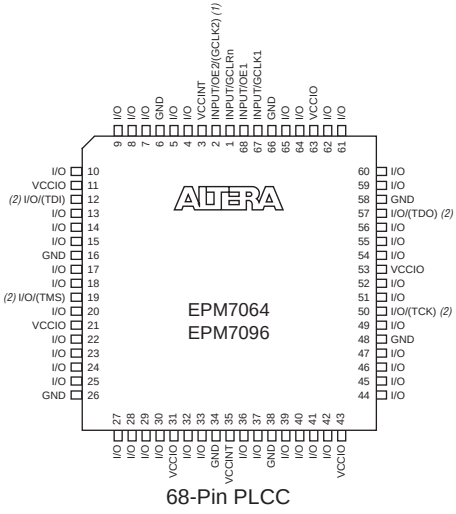
Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	149.3		122.0		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		0.9		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t_{H}	Register hold time		1.6		2.0		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t_{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t_{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t_{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns

Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

(1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.

(2) JTAG ports are available in MAX 7000S devices only.

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

- Reference to *AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor* has been replaced by *AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor*.

Version 6.6

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

Version 6.5

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.5:

- Updated text on page 16.

Version 6.4

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.4:

- Added *Note (5)* on page 28.

Version 6.3

The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.3:

- Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.

Notes: